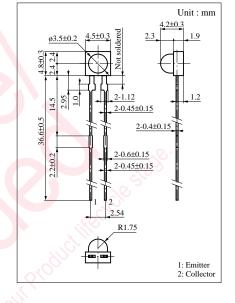
PNA2602M

Darlington Phototransistor

For optical control systems

Features

- Darlington output, high sensitivity
- Easy to combine light emission and photodetection on same printed circuit board
- Small size, thin side-view type package
- Long lead and visible light cutoff design with PN205



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

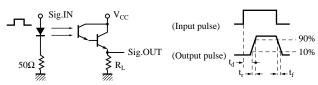
| Parameter | Symbol | Ratings | Unit |
|-------------------------------|------------------|---------------|------|
| Collector to emitter voltage | V _{CEO} | 20 | V |
| Emitter to collector voltage | V _{ECO} | 5 | V |
| Collector current | I_{C} | 30 | mA |
| Collector power dissipation | P _C | 100 | mW |
| Operating ambient temperature | T _{opr} | -25 to +80 | °C |
| Storage temperature | T_{stg} | -30 to +100 | °C |

■ Electro-Optical Characteristics (Ta = 25°C)

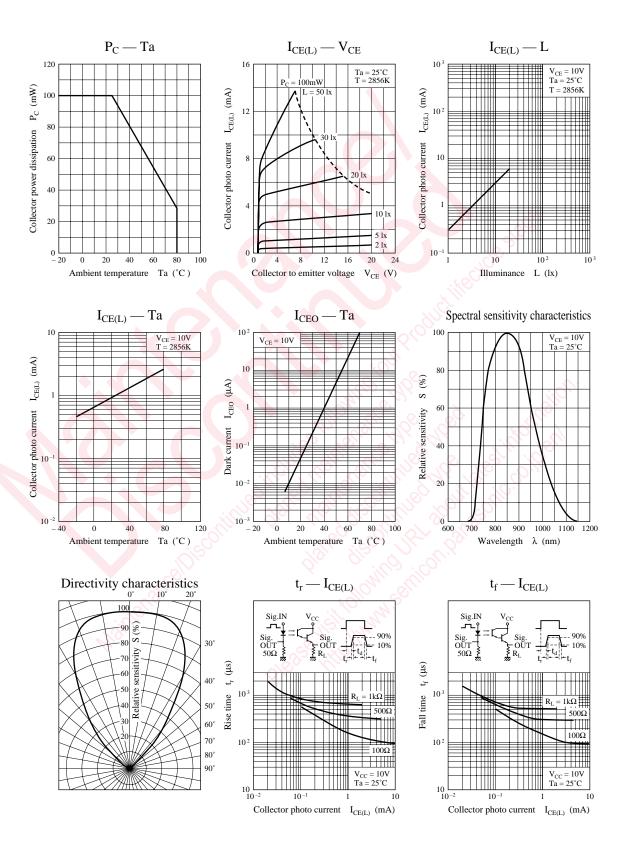
| Parameter | Symbol | Conditions | min | typ | max | Unit |
|----------------------------------|-------------------------|--|-----|-----|-----|------|
| Dark current | I_{CEO} | $V_{CE} = 10V$ | 9. | | 0.5 | μΑ |
| Sensitivity to infrared emitters | S _{IR} *1 | $V_{CE} = 10V, H = 3.75 \mu\text{W/cm}^2$ | 0.1 | | 3.0 | mA |
| Peak sensitivity wavelength | λ_{P} | $V_{CE} = 10V$ | | 850 | | nm |
| Acceptance half angle | θ | Measured from the optical axis to the half power point | | 35 | | deg. |
| Response time | t_r, t_f^{*2} | $V_{CC} = 10V, I_C = 1mA, R_L = 100\Omega$ | | 150 | | μs |
| Collector saturation voltage | V _{CE(sat)} *1 | $I_C = 100 \mu A, H = 3.75 \ \mu W/cm^2$ | | | 1.5 | V |

^{*1} Measurements were made using infrared light ($\lambda = 940$ nm) as a light source.

^{*2} Switching time measurement circuit



- t_d: Delay time
- $\rm t_r$: Rise time (Time required for the collector photo current to increase from 10% to 90% of its final value)
- $t_{\rm f}$: Fall time (Time required for the collector photo current to decrease from 90% to 10% of its initial value)



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